

Copper@-plated laminate mfr. for printed boards - by laying face of glass paper sheet impregnated with poly-hydric alcoholic methacrylate, or bisphenol-A polyepoxy resin with copper@ foil

Patent Assignee: MATSUSHITA ELECTRIC WORKS LTD (MATW)

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Abstract (Basic): JP 8118542 A

Mfr. comprises laying each face of (A) a glass paper sheet impregnated with a resin varnish contg.: (a) radical polymerising thermosetting resin; (b) inorganic filler; and (c) polyhydric alcoholic methacrylate; or (c') bisphenol-A epoxy resin or novolak epoxy resin with (B) glass cloth impregnated with the resin varnish and laying face(s) of the obtd. laminate with a Cu foil.

USE - Used in printed boards.

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Title Terms: COPPER; PLATE; LAMINATE; MANUFACTURE; PRINT; BOARD; LAY; FACE; GLASS; PAPER; SHEET; IMPREGNATE; POLY; HYDRIC; ALCOHOLIC; METHACRYLATE; BISPHENOL-A; POLYEPOXIDE; RESIN; COPPER; FOIL

Derwent Class: A12; A21; A32; A85; L03; P73; V04

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